

## CLAIMS

1. A polishing composition comprising:  
silica particles;  
water;  
a basic material; and  
an inorganic salt such as alkali metal salt and ammonium salt.
2. The polishing composition of claim 1, wherein an alkali metal salt or an ammonium salt such as KCl, K<sub>2</sub>SO<sub>4</sub>, KNO<sub>3</sub>, NaCl, Na<sub>2</sub>SO<sub>4</sub>, NaNO<sub>3</sub>, NH<sub>4</sub>Cl, NH<sub>4</sub>NO<sub>3</sub>, and (NH<sub>4</sub>)<sub>2</sub>SO<sub>4</sub> is used as the inorganic salt.
3. The polishing composition of claim 2, wherein the silica particles do not aggregate soon after the inorganic salt is added to the composition.
4. A polishing method for performing polishing while continuously feeding a polishing composition between a polishing pad and a polishing sample, wherein the polishing composition of claim 1, 2, or 3 is used as the polishing composition.